PC922

High Power OPIC Photocoupler

❋ Lead forming type（I type ）and taping reel type（P type ）are also available.（**PC922I/PC922P**）
❋❋ TÜV (VDE 0884) approved type is also available as an option.

■ Features

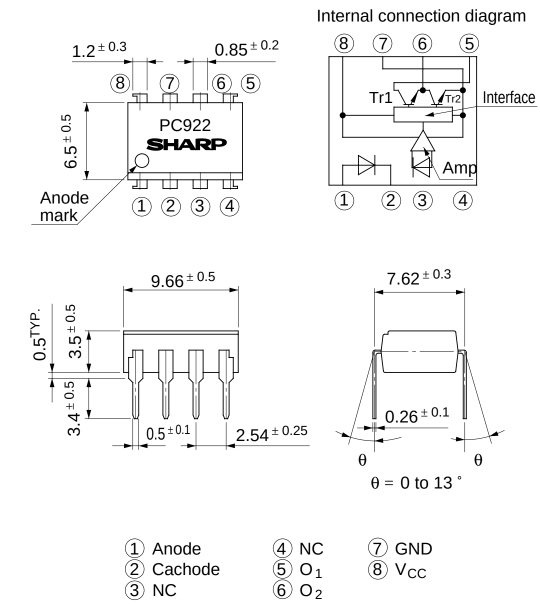
1. Built-in base amplifier for inverter drive
2. High power（I_{O1}: MAX. 0.5A（DC））
 (I_{O2P} : MAX. 2.0A（pulse ））
3. High isolation voltage between input and output（V_{iso} : 5 000V $_{rms}$）
4. High noise reduction type
5. High speed response（t_{PHL} , t_{PLH} : MAX. 5μs）
6. High sensitivity（I_{FLH} : MAX. 3mA ）
7. Recognized by UL, file No. E64380

■ Applications

1. Inverter controlled air conditioners
2. Small capacitance general purpose inverters

■ Outline Dimensions

(Unit : mm)



* " OPIC " (Optical IC) is a trademark of the SHARP Corporation. An OPIC consists of a light-detecting element and signal-processing circuit integrated onto a single chip.

■ Absolute Maximum Ratings

(Ta = T_{opr} unless otherwise specified)

Parameter		Symbol	Rating	Unit
Input	Forward current	I_F	25	mA
	*1 Reverse voltage	V_R	6	V
Output	Supply voltage	V_{CC}	18	V
	O_1 output current	I_{O1}	0.5	A
	*2 O_1 peak output current	I_{O1P}	1.0	A
	O_2 output current	I_{O2}	0.6	A
	*2 O_2 peak output current	I_{O2P}	2.0	A
	O_1 output voltage	V_{O1}	18	V
	Power dissipation	P_O	500	mW
Total power dissipation		P_{tot}	550	mW
*3 Isolation voltage		V_{iso}	5 000	V_{rms}
Operating temperature		T_{opr}	- 20 to + 80	˚C
Storage temperature		T_{stg}	- 55 to + 125	˚C
*4 Soldering temperature		T_{sol}	260	˚C

*1 Ta = 25˚C
*2 Pulse width <= 5μs, Duty ratio : 0.01
*3 40 to 60% RH, AC for 1 minute, Ta = 25˚C
*4 For 10 seconds

■ Electro-optical Characteristics

(Ta= T_{opr} unless otherwise specified)

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit	Fig.
Input	Forward voltage	V_{F1}	T_a = 25˚C, I_F = 5mA	-	1.1	1.4	V	-
		V_{F2}	T_a = 25˚C, I_F = 0.2mA	0.6	0.9	-	V	-
	Reverse current	I_R	T_a = 25˚C, V_R = 3V	-	-	10	μA	-
	Terminal capacitance	C_t	T_a = 25˚C, V = 0, f = 1kHz	-	30	250	pF	-
Output	Operating supply voltage	V_{CC}		5.4	-	13	V	-
	O_1 low level output voltage	V_{O1L}	V_{CC} = 6V, I_{O1} = 0.4A, R_{L2} = 10Ω, I_F = 5mA	-	0.2	0.4	V	1
	O_2 high level output voltage	V_{O2H}	V_{CC} = 6V, I_{O2} = - 0.4A, I_F = 5mA	4.5	5.0	-	V	2
	O_2 low level output voltage	V_{O2L}	V_{CC} = 6V, I_{O2} = 0.5A, I_F = 0	-	0.2	0.4	V	-
	O_1 leak current	I_{O1L}	V_{CC} = 13V, I_F = 0	-	-	200	μA	3
	O_2 leak current	I_{O2L}	V_{CC} = 13V, I_F = 5mA	-	-	200	μA	4
	High level supply current	I_{CCH}	T_a = 25˚C, V_{CC} = 6V, I_F = 5mA	-	9	13	mA	-
			V_{CC} = 6V, I_F = 5mA	-	-	17	mA	-
	Low level supply current	I_{CCL}	T_a = 25˚C, V_{CC} = 6V, I_F = 0	-	11	15	mA	-
			V_{CC} = 6V, I_F = 0	-	-	20	mA	-
Transfer charac-teristics	*5 "Low→High" threshold input current	I_{FLH}	T_a = 25˚C, V_{CC} = 6V, R_{L1} = 5Ω, R_{L2} = 10Ω	0.3	1.5	3.0	mA	5
			V_{CC} = 6V, R_{L1} = 5Ω, R_{L2} = 10Ω	0.2	-	5.0	mA	5
	Isolation resistance	R_{ISO}	Ta = 25˚C, DC = 500V, 40 to 60% RH	5×10^{10}	10^{11}	-	Ω	-
	Response time: "Low→High" propagation delay time	t_{PLH}	T_a = 25˚C, V_{CC} = 6V, I_F = 5mA R_{L1} = 5Ω, R_{L2} = 10Ω	-	2	5	μs	6
	Response time: "High→Low" propagation delay time	t_{PHL}		-	2	5	μs	
	Response time: Rise time	t_r		-	0.2	1	μs	
	Response time: Fall time	t_f		-	0.1	1	μs	
	Instantaneous common mode rejection voltage "Output : High level"	CM_H	T_a = 25˚C, V_{CM} = 600V(peak), I_F = 5mA, R_{L1} = 470Ω, R_{L2} = 1kΩ, ΔV_{O2H} = 0.5V	-1 500	-	-	V/μs	7
	Instantaneous common mode rejection voltage "Output : Low level"	CM_L	T_a = 25˚C, V_{CM} = 600V(peak), I_F = 0, R_{L1} = 470Ω, R_{L2} = 1kΩ, ΔV_{O2L} = 0.5V	1 500	-	-	V/μs	7

*5 I_{FLH} represents forward current when output goes from low to high.

■ Truth Table

Input	O_2 Output	Tr. 1	Tr. 2
ON	High level	ON	OFF
OFF	Low level	OFF	ON

■ Test Circuit

Fig. 1

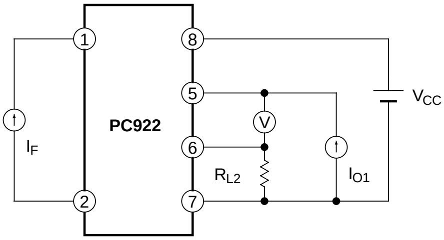


Fig. 2

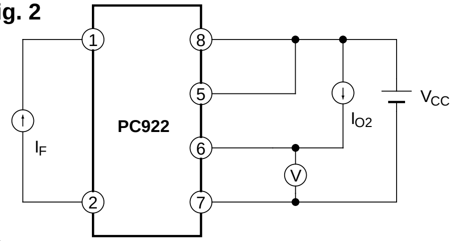


Fig. 3

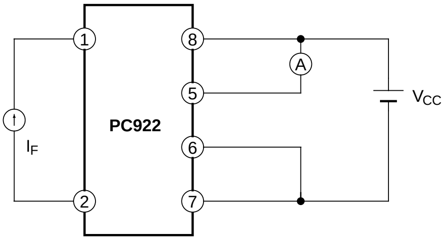


Fig. 4

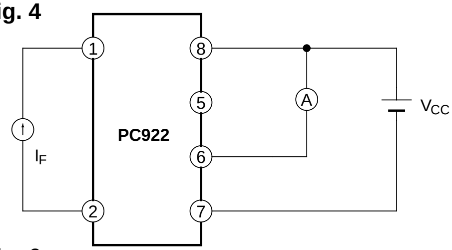


Fig. 5

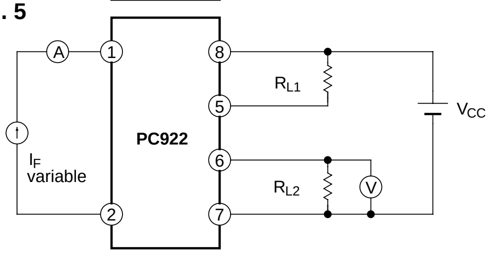


Fig. 6

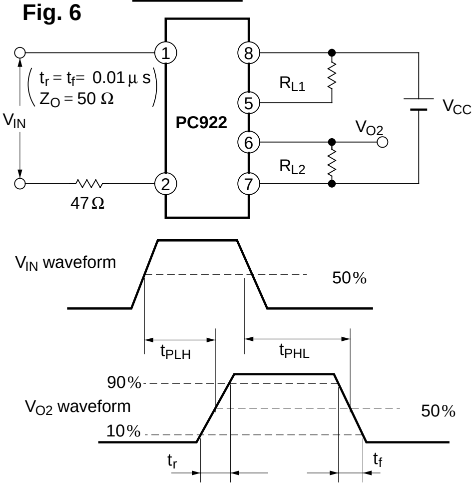


Fig. 7

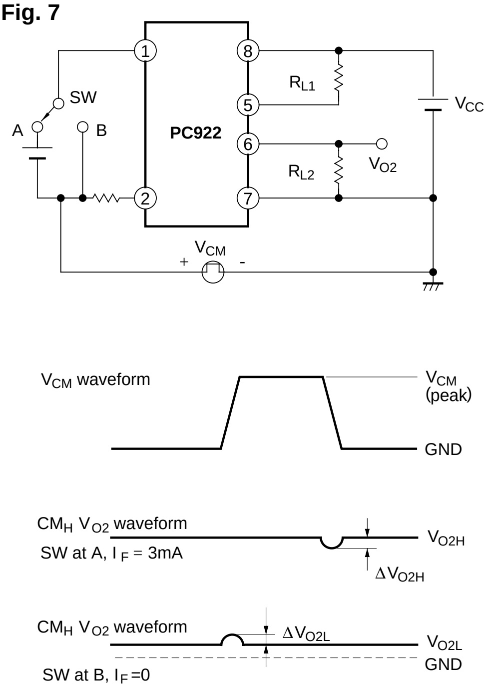


Fig. 8 Forward Current vs. Ambient Temperature

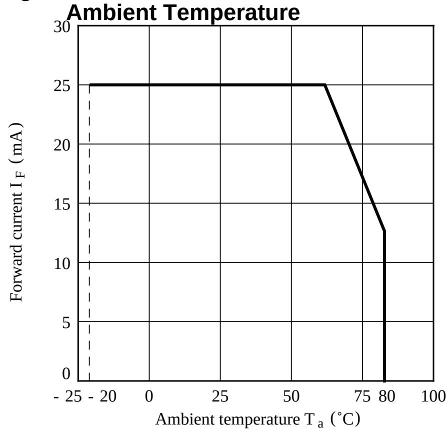


Fig. 9-a Power Dissipation vs. Ambient Temperature

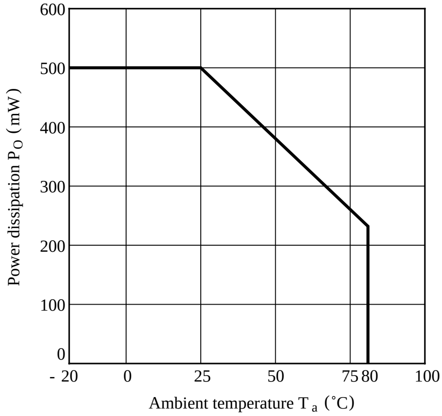


Fig. 9-b Power Dissipation vs. Ambient Temperature

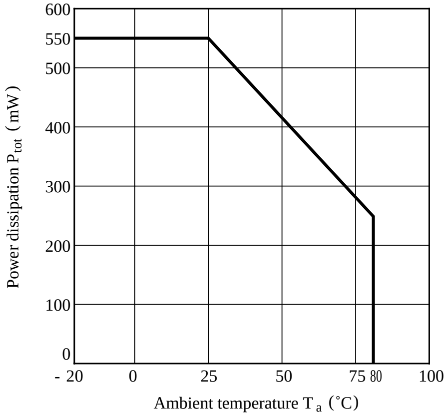


Fig. 10 Forward Current vs. Forward Voltage

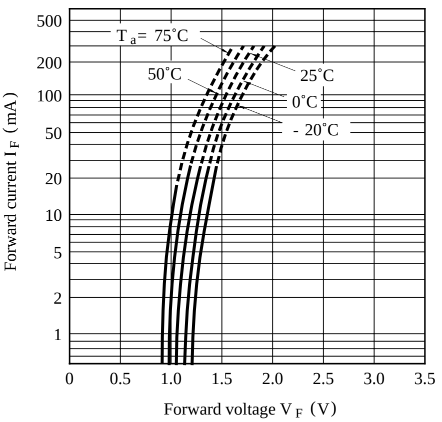


Fig.11 " Low→High " Relative Threshold Input Current vs. Supply Voltage

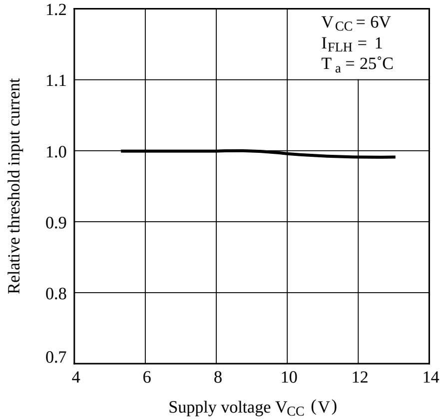


Fig.12 " Low→High " Relative Threshold Input Current vs. Ambient Temperature

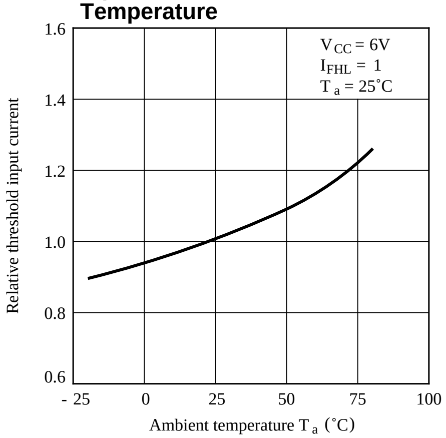


Fig.13 O_1 Low Level Output Voltage vs. O_1 Output Current

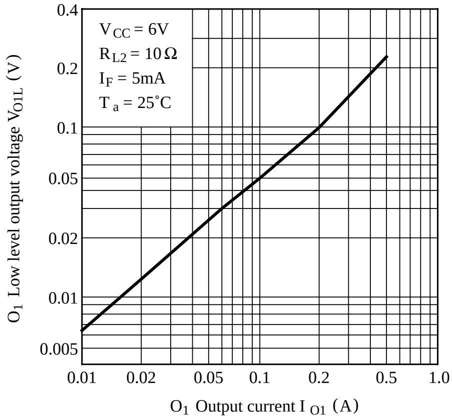


Fig.14 O_1 Low Level Output Voltage vs. Ambient Temperature

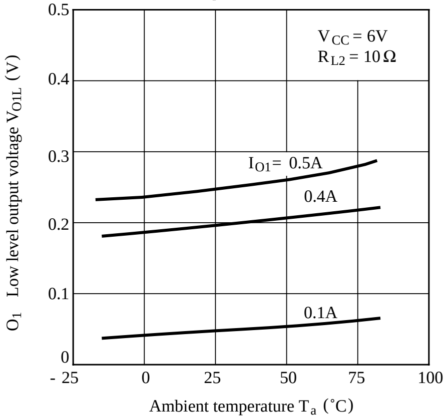


Fig.15 O_2 High Level Output Voltage vs. O_2 Output Current

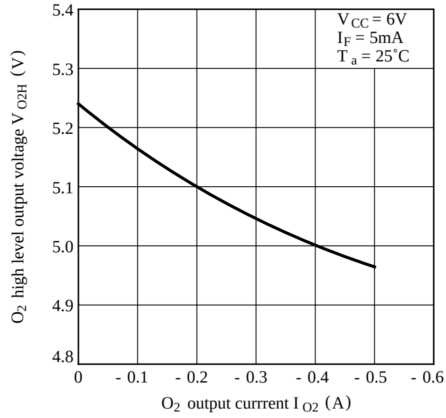


Fig.16 O_2 High Level Output Voltage vs. Ambient Temperature

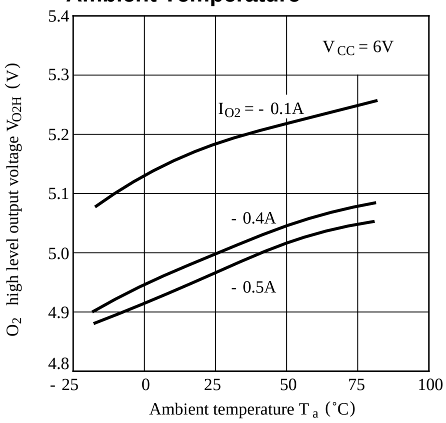


Fig.17 O_2 Low Level Output Voltage vs. O_2 Output Current

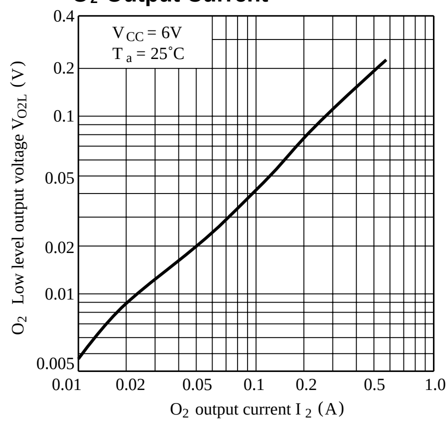


Fig.18 O_2 Low Level Output Voltage vs. Ambient Temperature

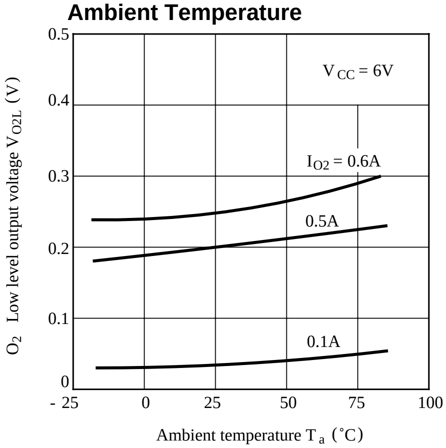


Fig.19 High Level Supply Current vs. Supply Voltage

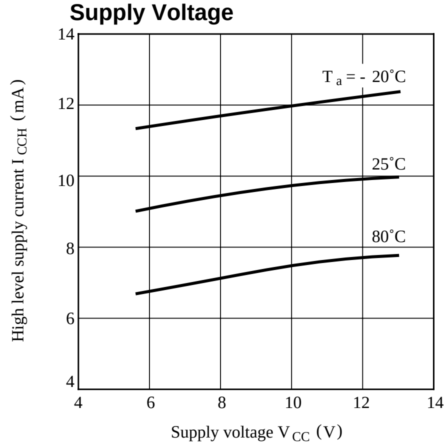


Fig.20 Low Level Supply Current vs. Supply Voltage

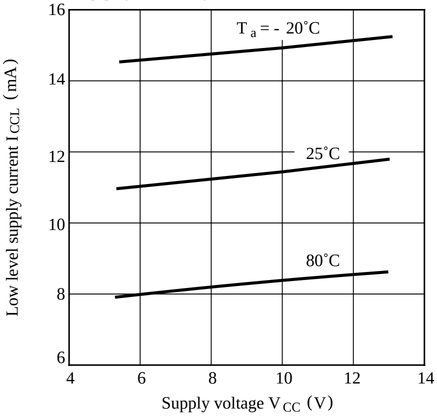


Fig.21 Propagation Delay Time vs. Forward Current

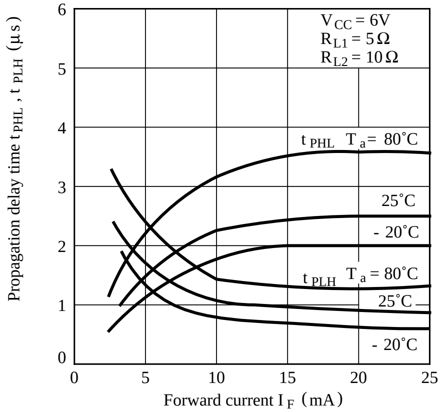


Fig.22 Propagation Delay Time vs. Ambient Temperature

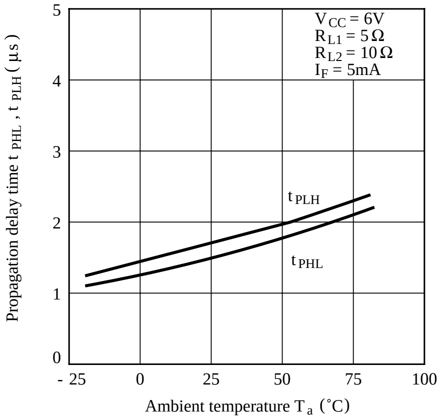
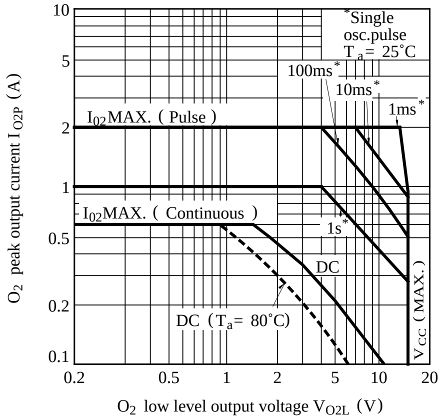
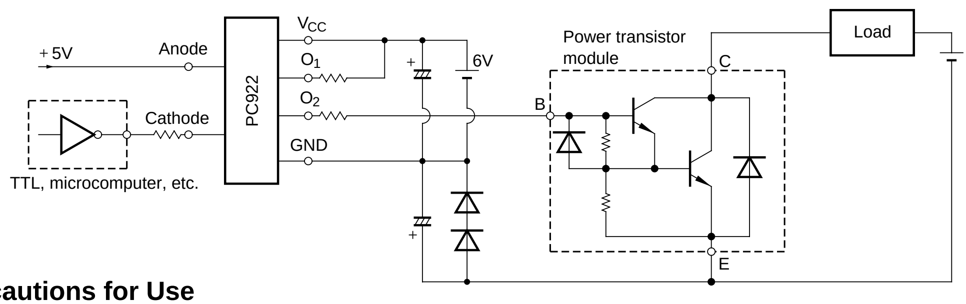


Fig.23 O_2 Peak Output Current vs. O_2 Low Level Output Voltage



■ Application Circuit



■ Precautions for Use

(1) It is recommended that a by-pass capacitor of more than 0.01 μ F is added between V_{CC} and GND near the device in order to stabilize power supply line.

(2) Handle this product the same as with other integrated circuits against static electricity.

(3) As for other general cautions, refer to the chapter "Precautions for Use".